2274000-1 <

TE Internal #: 2274000-1 SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > zSFP+ Cage Assembly: EMI Springs



Pluggable I/O Product Type: Cage Assembly Data Rate (Max): 32 Gb/s EMI Containment Feature Type: Internal/External EMI Springs Pluggable I/O Applications: zSFP+ Thermally Enhanced Lightpipe Options: With Lightpipe All zSFP+ Cage Assembly: EMI Springs (25)

Features

Product Type Features

Form Factor

zSFP+

Circold

Cage Туре	Single
Pluggable I/O Product Type	Cage Assembly
Lightpipe Options	With Lightpipe
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Port Matrix Configuration	1 x 1
Lightpipe Configuration	Dual Round
Lightpipe Style	Standard
Lightpipe Profile	Standard
Number of Ports	1
Electrical Characteristics	
Data Rate (Max)	32 Gb/s
Termination Features	

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round



Termination Post & Tail Length	3 mm[.118 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Cage Material	Nickel Silver Alloy
Dimensions	
PCB Thickness (Recommended)	1.5 mm[.059 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Heat Sink Compatible	No
For Use With Pluggable I/O Products	zSFP+ SMT Connector
Pluggable I/O Applications	zSFP+ Thermally Enhanced
Circuit Application	Signal
Packaging Features	

Packaging Method

Other

EMI Containment Feature Type

Internal/External EMI Springs

Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not applicable for solder process capability

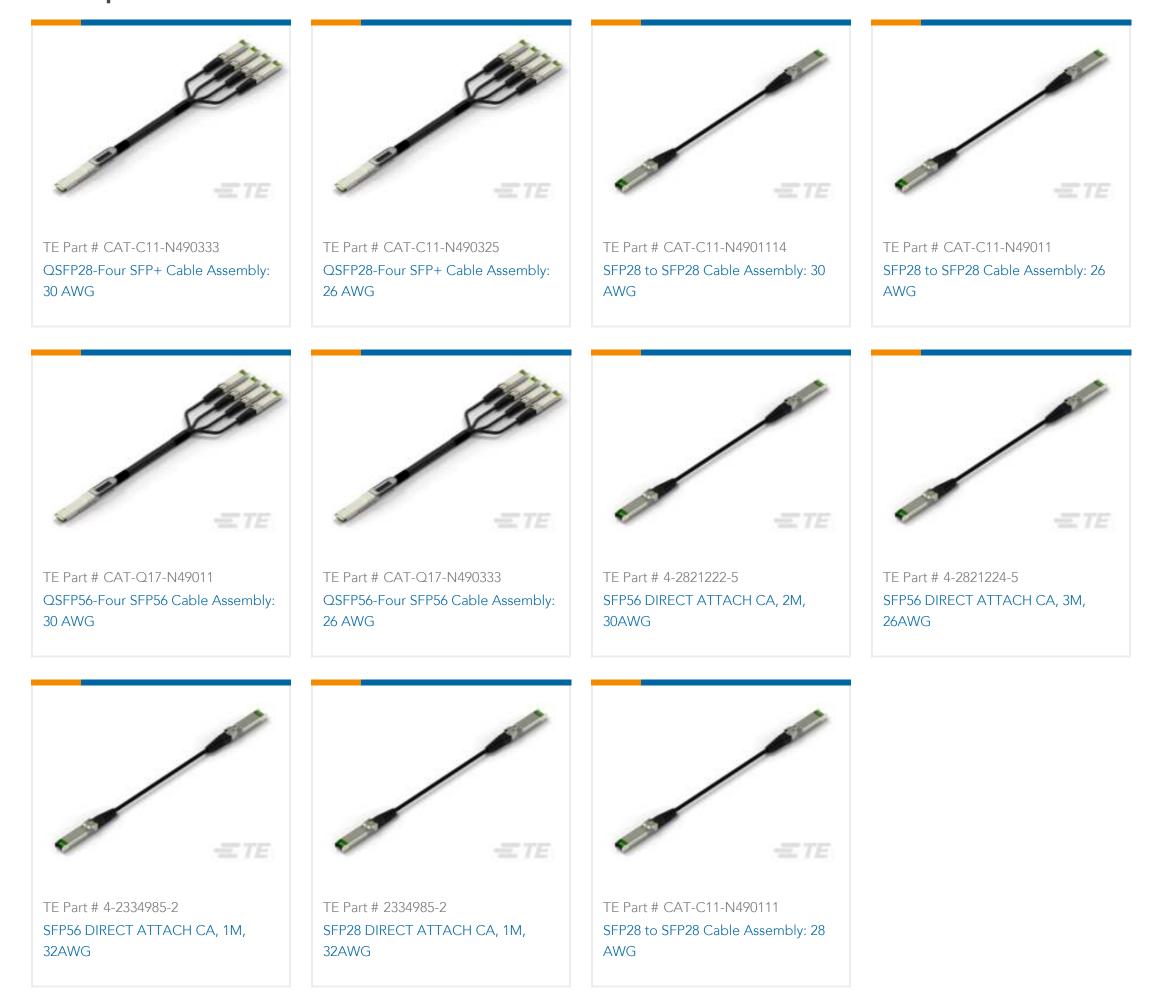
SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round



Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

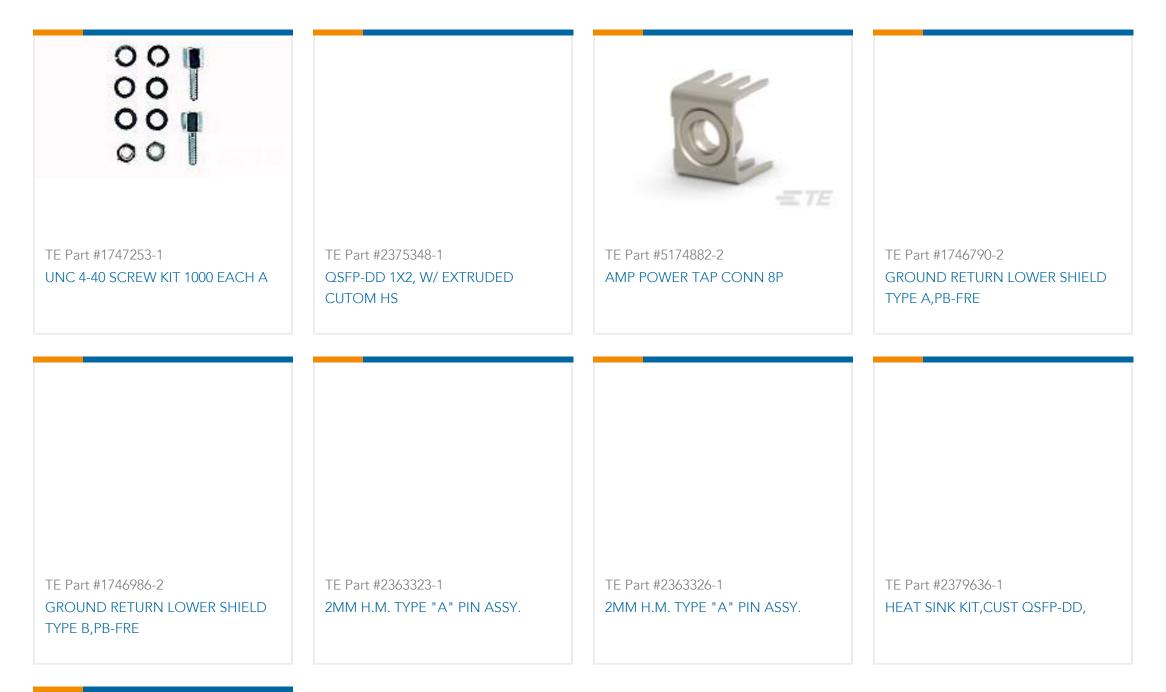
Compatible Parts

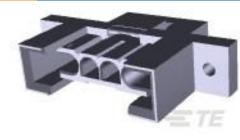


Customers Also Bought

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round







TE Part #176416-1 U-M-N-L D-TYPE CAP KIT 4P

Documents

Product Drawings ZSFP+ 1X1 CAGE ASSEMBLY PRESSFIT WITH LP

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2274000-1_A.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_2274000-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2274000-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

C For support call+1 800 522 6752

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, zSFP+ Thermally Enhanced, With Lightpipe, 1 x 1, Dual Round



zSFP+ Interconnect Brochure

English

Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English